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Brighten Up The World With LED!



ISO/TS 16949:2009



BS EN ISO 14001:2004



QC 080000 IECQ HSPM

PRODUCT DATASHEET

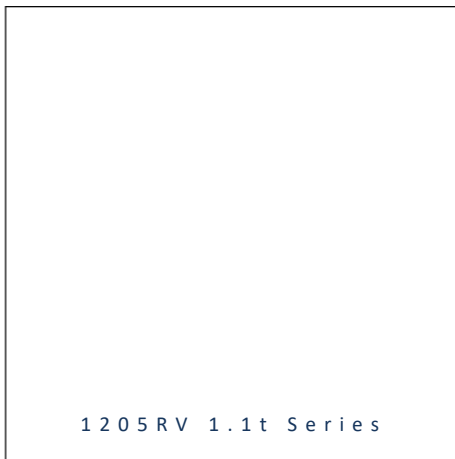


- ▶ PCB Reverse Mount
- ▶ 1205RV 1.1t Series
- ▶ Red (631nm) / Green (573nm)

NOD39S41RV



Release Date: 22 March 2017 Version: A1.0



1205RV 1.1t Series

1205RV 1.1t Series

RoHS
Compliant



FEATURES:

- **Package:** PCB Reverse Mount SMT Package Duo Colours
- **Forward Current:** 20/20mA*
- **Forward Voltage (typ.):** 2.0/2.0V
- **Luminous Intensity (typ.):** 50/50mcd@20mA
- **Colour:** Red/Green
- **Wavelength:** 631/573nm
- **Viewing angle:** 130/130°
- **Materials:**
 - Die: AlGaInP/AlGaInP
 - Resin: Epoxy (Water Clear)
- **Operating Temperature:** -40~+85°C
- **Storage Temperature:** -40~+90°C
- **ESD:** 2000/2000V
- **Grouping parameters:**
 - Forward voltage
 - Luminous intensity
 - Dominant Wavelength
- **Soldering methods:** Reflow
- **Preconditioning:** acc. to JEDEC Level 3
- **Packing:** 8mm tape with 2000/reel, ø180mm (7")

* in the order of Red/Green

APPLICATIONS:

- Indication Light
- Switch light
- Dashboard
- Keyboard
- Consumer Goods

CHARACTERISTICS:

Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Forward Current	I _F	25/25*	mA
Peak Forward Current Duty 1/10@1KHz	I _{FP}	60/60	mA
Reverse Voltage ₀	V _R	5/5	V
Reverse Current @5V	I _R	10/10	μA
Power Dissipation	PD	60/60	mW
Electrostatic Discharge	ESD	2000/2000	V
Operating Temperature	T _{OPR}	-40~+85	°C
Storage Temperature	T _{STG}	-40~+90	°C

* in the order of Red/Green

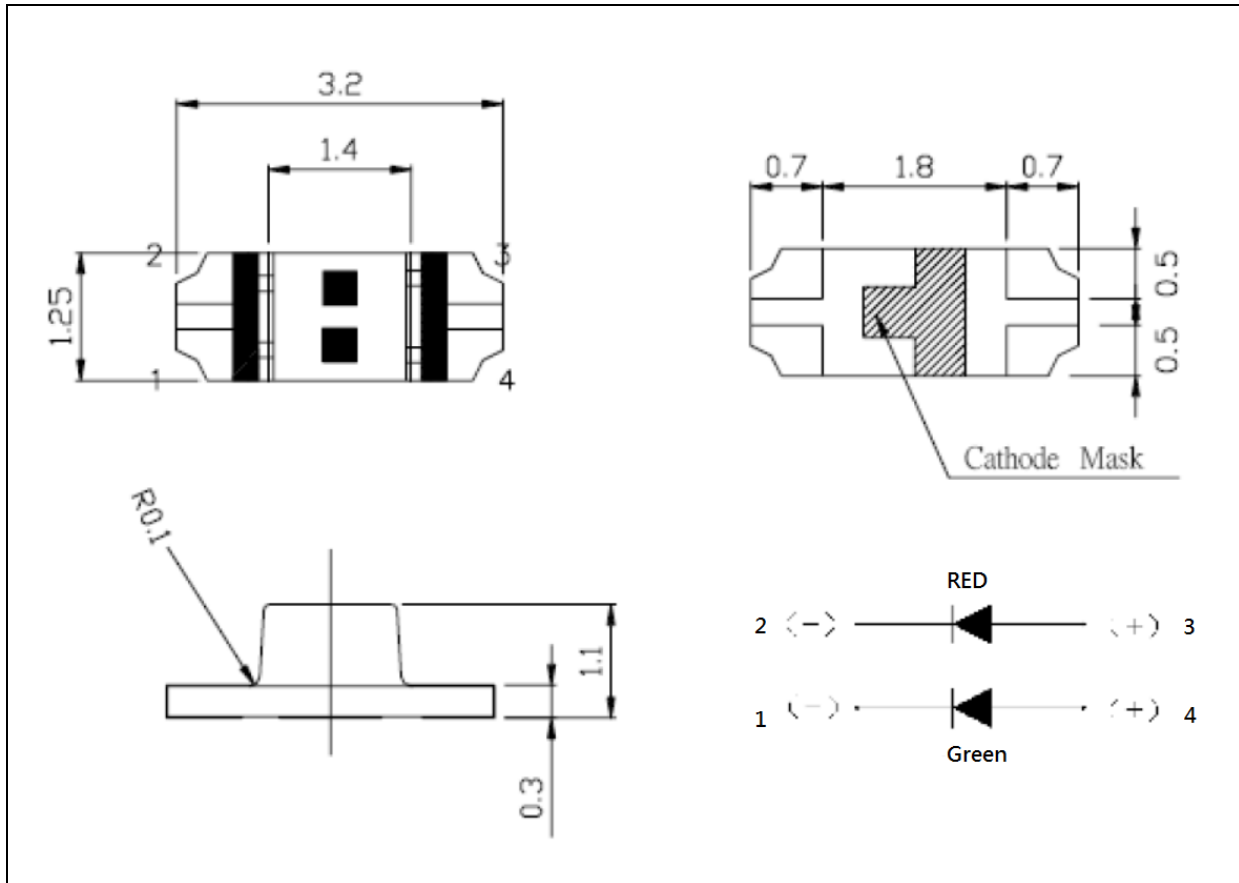
Electrical & Optical Characteristics (Ta=25°C)

Parameter	Symbol	Values			Unit	Test Condition
		Min.	Typ.	Max.		
Forward Voltage	V _F	1.7/1.7	2.0/2.0	2.4/2.4	V	I _F =20mA
Luminous Intensity	I _v	28.5/28.5	---	72/72	mcd	I _F =20mA
Dominant Wavelength	λ _D	---	631/573	---	nm	I _F =20mA
Peak Wavelength	λ _P	---	639/575	---	nm	I _F =20mA
Spectral Line Half Bandwidth	Δλ	---	20/20	---	nm	I _F =20mA
Viewing Angle	2θ _{1/2}	---	130/130	---	deg	I _F =20mA

- Luminous intensity (I_v) ±15%, Forward Voltage (V_F) ±0.1V

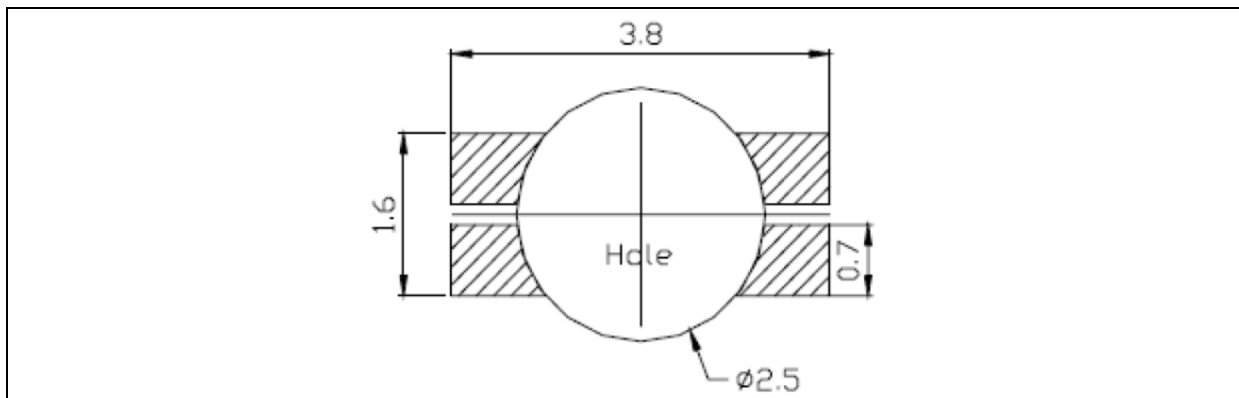
OUTLINE DIMENSION:

Package Dimension:



1. All dimensions are in millimetre (mm).
2. Tolerance ± 0.1 mm, unless otherwise noted.

Recommended Soldering Pad Dimension:



1. Dimensions are in millimetre (mm).
2. Tolerance ± 0.1 mm with angle tolerance $\pm 0.5^\circ$.

BINNING GROUPS:

 Forward Voltage Classifications ($I_F = 20\text{mA}$):

Code	Min.	Max.	Unit
Red	1.7	2.4	V
Green	1.7	2.4	

 Luminous Intensity Classifications ($I_F = 20\text{mA}$):

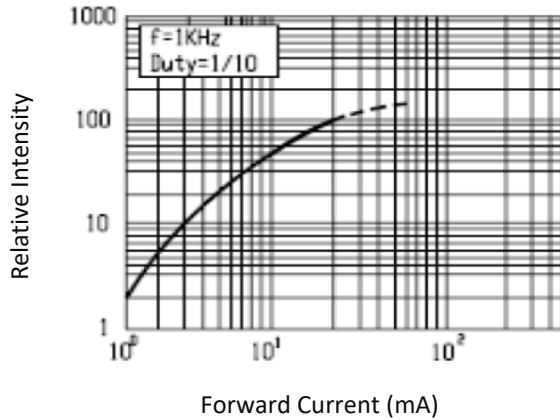
Code	Min.	Max.	Unit
Red	R1	28.5	mcd
	R2	45	
Green	G1	28.5	mcd
	G2	45	

 Dominant Wavelength Classifications ($I_F = 20\text{mA}$):

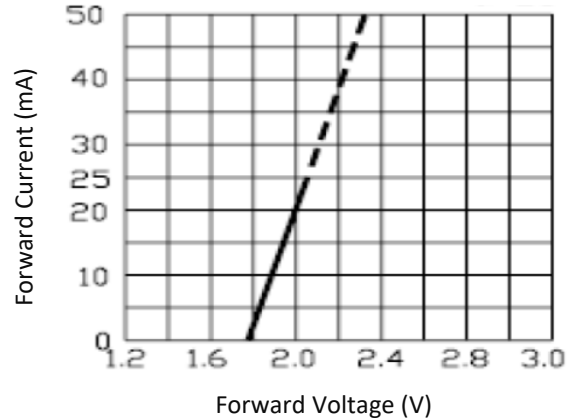
Code	Min.	Max.	Unit
Red	624	637	nm
Green	566	579	nm

ELECTRO-OPTICAL CHARACTERISTICS (RED):

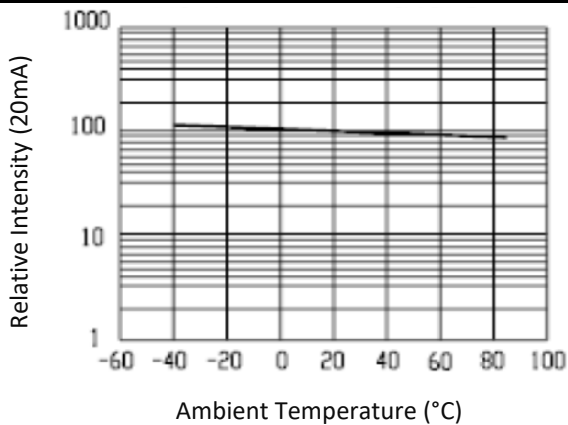
Relative Intensity v.s. Forward Current



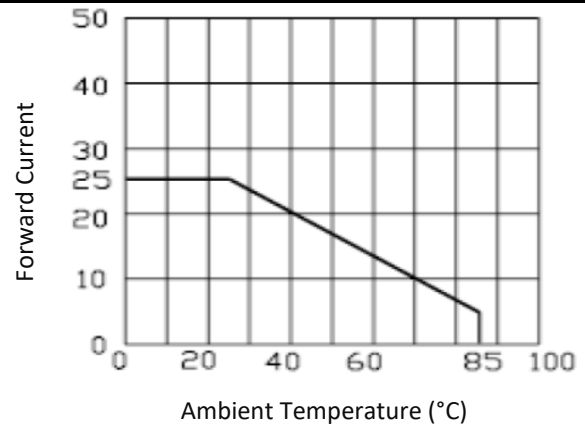
Forward Current v.s. Forward Voltage



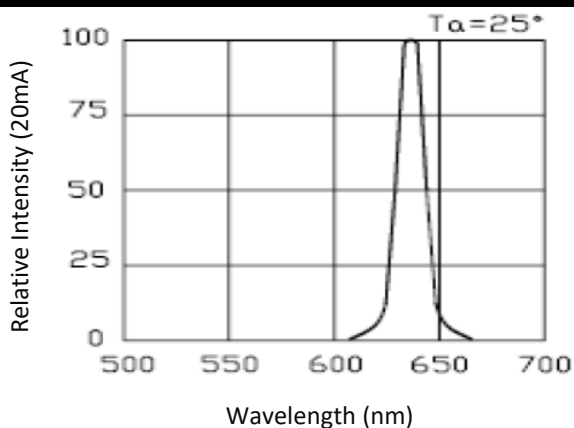
Relative Intensity v.s. Temperature



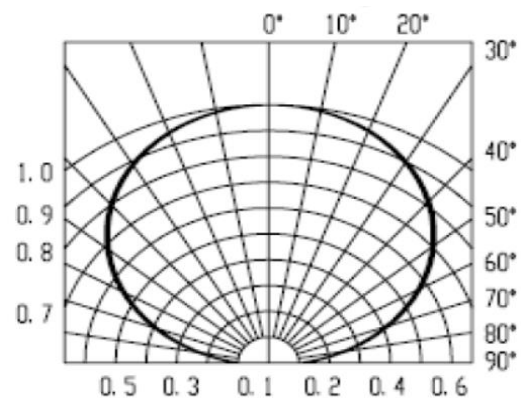
Forward Current v.s. Temperature



Relative Intensity v.s. Wavelength

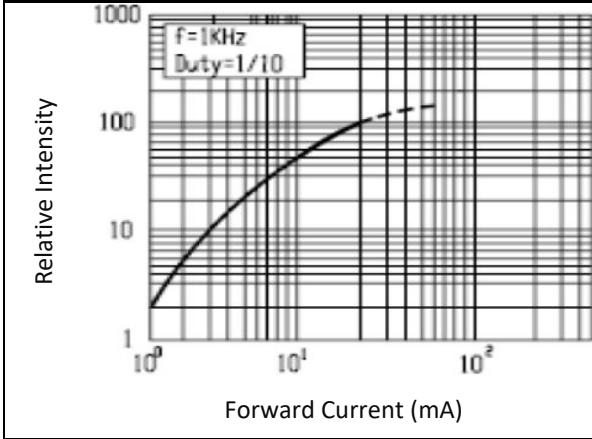


Directive Radiation

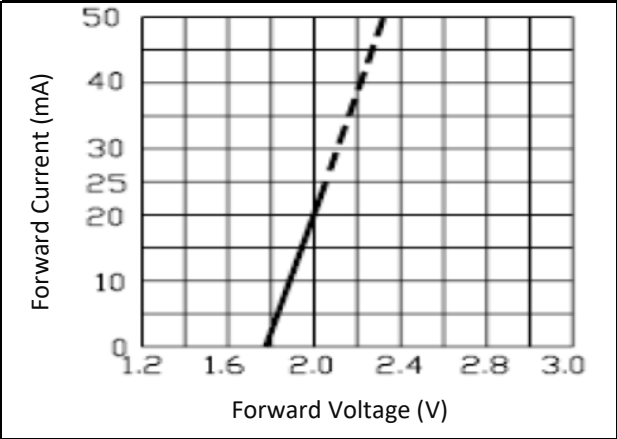


ELECTRO-OPTICAL CHARACTERISTICS (GREEN):

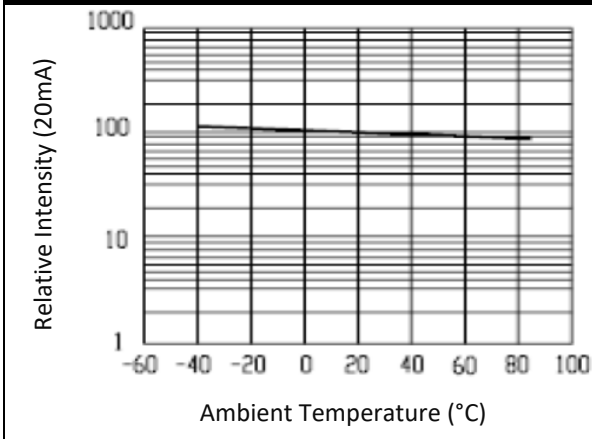
Relative Intensity v.s. Forward Current



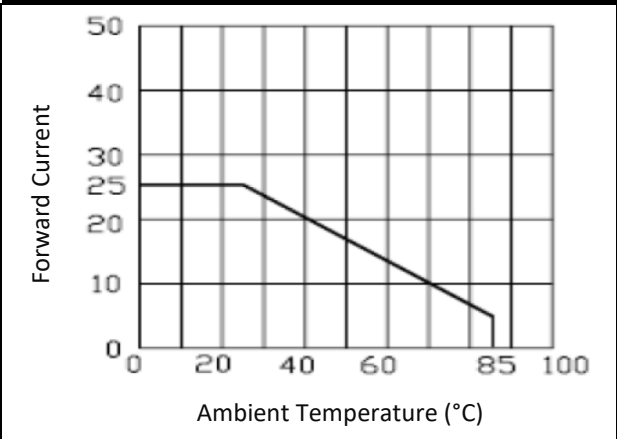
Forward Current v.s. Forward Voltage



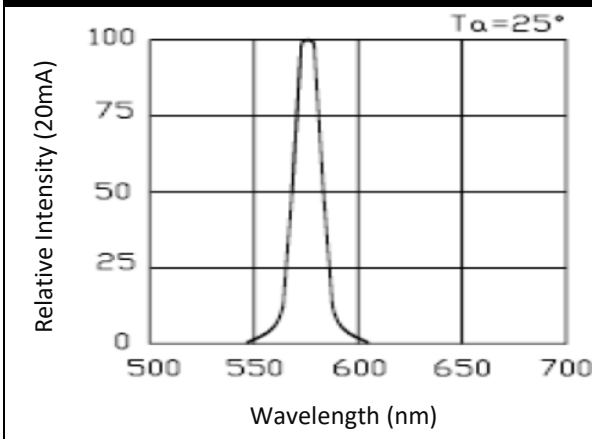
Relative Intensity v.s. Temperature



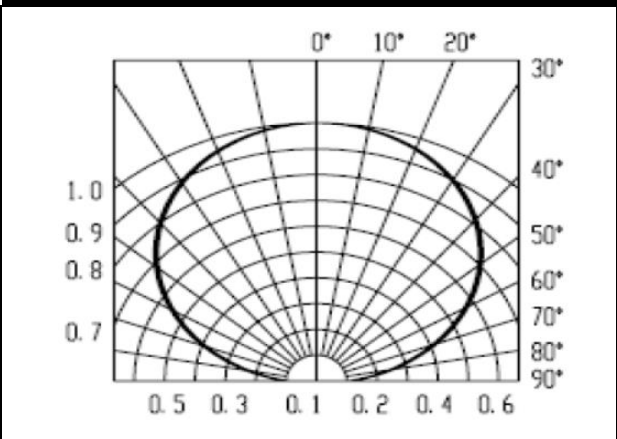
Forward Current v.s. Temperature



Relative Intensity v.s. Wavelength

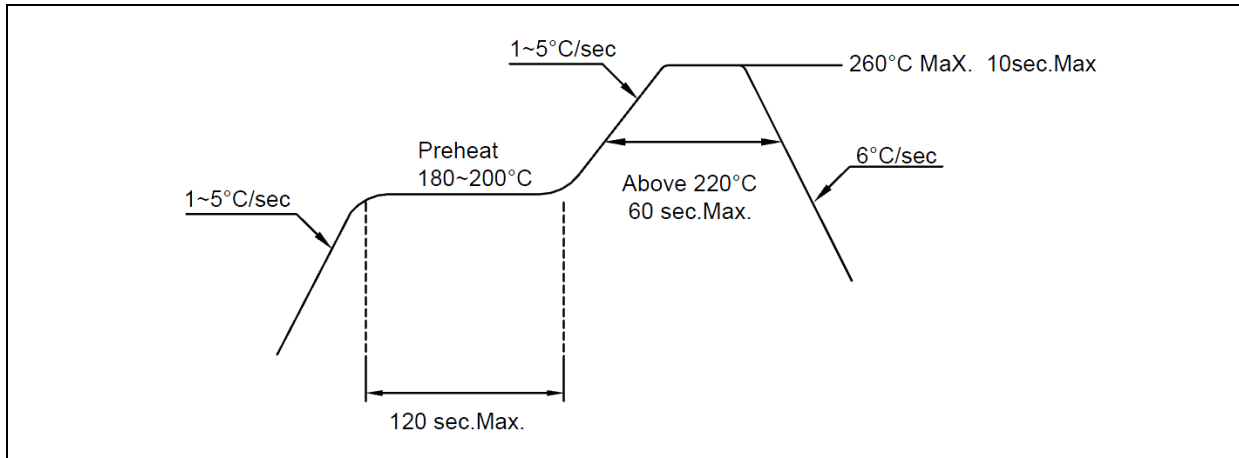


Directive Radiation



RECOMMENDED SOLDERING PROFILE:

Lead-free Solder:

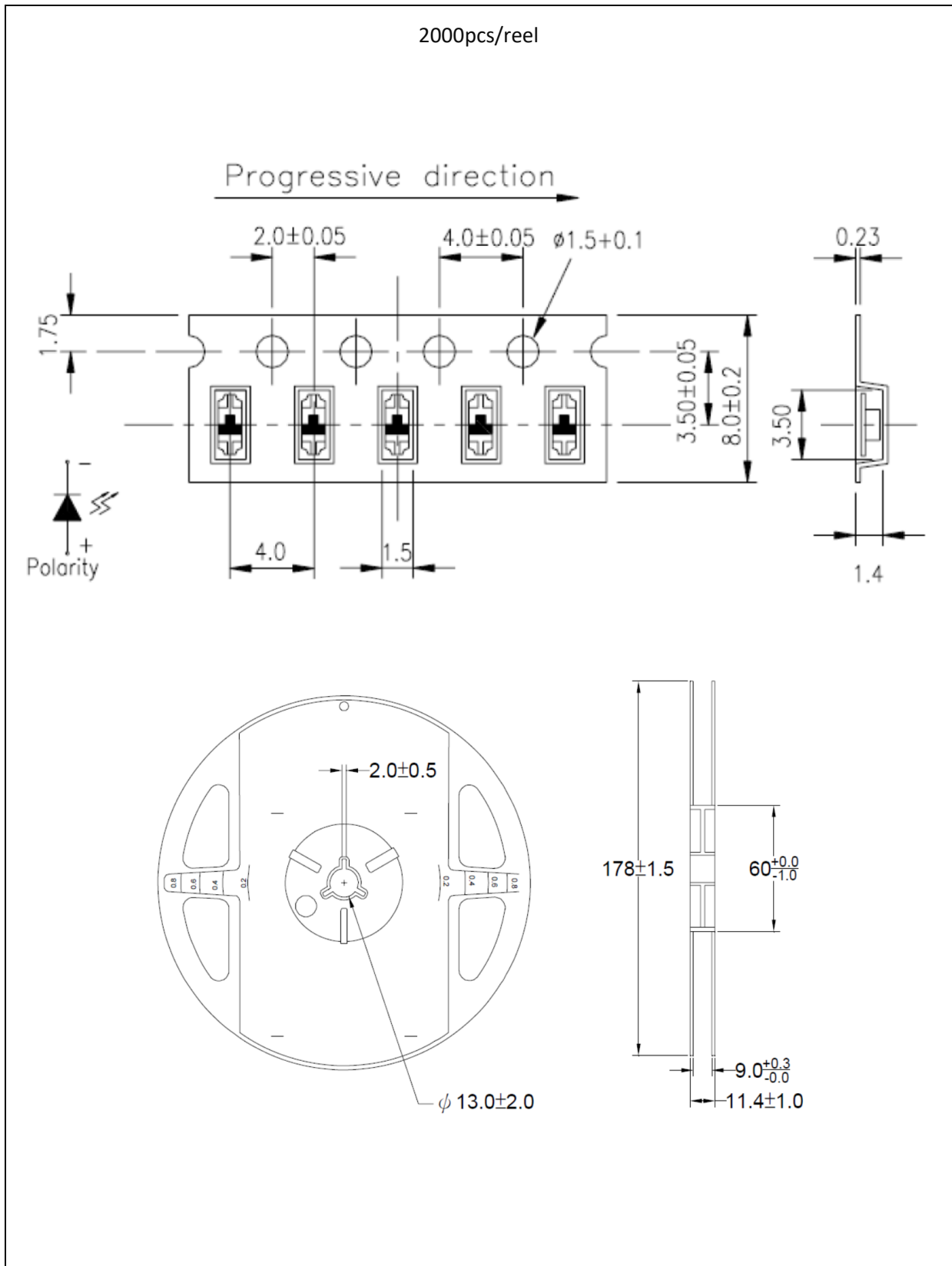


Note:

1. Maximum reflow soldering: 2 times.
2. Before, during, and after soldering, should not apply stress on the components and PCB board.

PACKING SPECIFICATION:

Reel Dimension:



PRECAUTIONS OF USE:

Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~35°C (41°F ~86°F).

Shelf life in sealed bag: 12 month at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with desiccating agent and apply baking at 60°C±5°C for 15hrs before use.

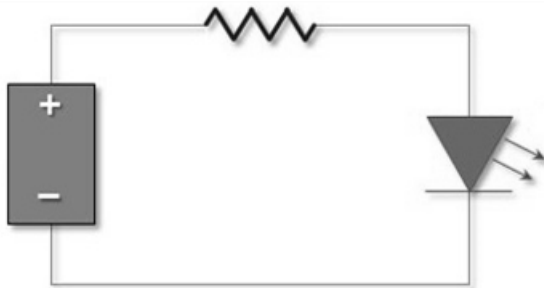
Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

- 60±3°C x 24hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Testing Circuit:



Must apply resistor(s) for protection (over current proof).

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handling the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.

REVISION RECORD:

Version	Date	Summary of Revision
A1.0	22/03/2017	Datasheet set-up.